

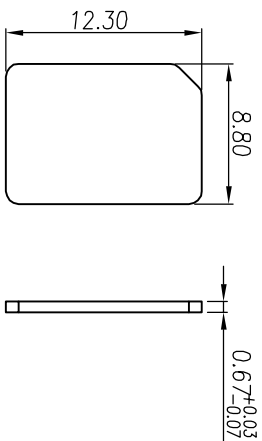


RECOMMENDED PCB LAYOUT

TOLERANCE: ± 0.05

-  SMT SOLDER AREA
-  COPPER RESTRICTED AREA
- 1. TOUCH AREA OF CONTACT
- TIPS NO ELECTRICAL FUNCTION
- 2. NO FIRST PCB LAYOUT
- CIRCUITS IN THE AREA



NOTES:

1. MATERIAL:

- HOUSING: High Temperature Thermoplastic
- Terminal: Copper Alloy
- Shell: Stainless Steel

2. PLATING:

- Terminal: 30μ" Ni UNDERPLATED OVERALL
- G/F PLATED ON CONTACT AREA
- 100μ" TIN PLATED ON SOLDER AREA
- Shell: 50μ" Ni UNDERPLATED OVERALL
- G/F PLATED ON CONTACT AREA AND SOLDER AREA

3. TECHNICAL SPECIALTY:

- RATED VOLTAGE: 30V AC MAX
- CURRENT RATING: 0.5A MAX
- INSULATION RESISTANCE: 1000MΩ MIN
- CONTACT RESISTANCE: 100mΩ MAX
- WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES
- OPERATING TEMPERATURE: -20°C ~ +85°C Humidity: 90%RH MAX

PIN/NO/ASSIGNMENT	
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

UNITS: mm	
GENERAL TOLERANCE	
X ± 5°	0.X ± 0.25
X ± 2°	0.XX ± 0.2
X ± 1°	0.XXX ± 0.1

**CSCONN**  
PART NO./INTENDED USE:  
CS106101103002

CSCONN PRECISE ELECTRONICS CO., LTD

TITLE: MAND SIM CARD GP H-1.13MM 抽屜式

DWG NO. SIM CARD



SCALE: 1:1  
SHEET: 1 OF 1  
REV: A

E

D

C

B

A

1 2 3 4 5 6 7 8